

Appl. No. 10/728,150
Amdt. dated March 12, 2007
Reply to Office action of December 12, 2006

REMARKS

The Examiner is thanked for the thorough examination and search of the subject.

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Claims 231-237, 244-246, 256-277, 279 and 320 are pending. Claims 231, 244-246, 256-258, 260, 264, 268, 277 and 279 are currently amended. Claim 320 is newly added. Claims 1-230, 238-243, 247-255, 278 and 280-319 are canceled.

10 Response to Objection

Reconsideration of objection to Claim 277 is requested in accordance with the following remarks.

15 Withdrawal of objection to Claim 277 is requested as applicants amended Claim 277.

Response to Claim Rejections under 35 U.S.C. 102 and 103

20 Applicants respectfully traverse the rejections for at least the reasons set forth below.

Response to Claims 231-237, 244-246, 256-277, 279 and 320

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As currently amended, independent claim 231 is recited below:

231. A circuit component comprising:

a first die having a top surface at a horizontal level;

a patterned wiring layer over said horizontal level, wherein said patterned

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wiring layer comprises a portion across a side of said die;

a first polymer layer over said horizontal level, wherein said first polymer layer is the only one polymer layer between said first die and said patterned wiring layer, said patterned wiring layer being connected to said first die through an opening in said first polymer layer;

a passive device over said horizontal level; and

a second polymer layer over said passive device.

10 Section I

Reconsideration of Claims 231, 232, 239-240, 243, 247, 251, 259-260, 264-265, 267-270 and 278-279 rejected under 35 U.S.C. 102(b) as being anticipated by Eichelberger (US 6,159,767), and of Claims 233-237, 244-246, 248-250, 252-254 and 266 rejected under 35 U.S.C. 103(a) as being unpatentable over Eichelberger in view of Foster et al. (US 6,603,072) and/or Yuyama et al. (US 6,620,513), and of Claims 261-263 and 271-276 rejected under 35 U.S.C. 103(a) as being unpatentable over Eichelberger is requested in accordance with the following remarks.

Applicants respectfully assert that the circuit component claimed in Claim 231 patentably distinguishes over the citations by Eichelberger (US 6,159,767).

Eichelberger teaches a circuit component comprising a first die 102 having a top surface at a horizontal level; a patterned wiring layer 110 over said horizontal level, wherein said patterned wiring layer 110 comprises a portion across a side of said die 102; a first dielectric layer 106 over said horizontal level, wherein said first dielectric layer is the only one dielectric layer between said first die 102 and said patterned wiring layer 110, said patterned wiring layer 110 being connected to said first die 102 through an opening in said first dielectric layer 106; and an electronic device 220 over said horizontal level.

~ See Figs. 5e-5h and 6; col. 12, lines 11-16 and 18-20 ~

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Eichelberger fails to teach the circuit component may comprise a polymer layer over said electronic device, such as passive device, as claimed in Claim 231. Furthermore, Eichelberger fails to teach said electronic device 220 may be a passive device, as claimed in Claim 231.

The Examiner considers that "the electronic component (220) connected to the active chips (102) is considered as a passive device (not active device)". ~ See lines 9-10, in the last paragraph, in the last Office Action mailed Dec. 12, 2006 ~

Applicants respectfully traverse the Examiner's opinion because Eichelberger fails to teach the electronic component (220) may be a passive device. Withdrawal of rejection under 35 U.S.C. 102(b) to Claim 231 is respectfully requested.

For at least the foregoing reasons, applicants respectfully submit independent Claim 231 patently distinguishes over the prior art references, and should be allowed. For at least the same reasons, dependent Claims 232-237, 244-246, 256-277, 279 and 320 patently define over the prior art as well.

Section II

Reconsiderations of Claims 231, 232, 236, 239, 240, 243, 244, 247, 248, 251, 252, 255, 256, 259, 260, 264, 271-273 and 277-279 rejected under 35 U.S.C. 102(b) as being anticipated by *Saia et al.* (US 5,874,770), of Claims 233-235, 237, 245, 246, 249, 250, 253, 254, 257 and 258 rejected under 35 U.S.C. 103(a) as being unpatentable over *Saia et al.* in view of *Foster et al.* (US 6,603,072) and/or *Yuyama et al.* (US 6,620,513), and of Claims 261-263 and 274-276 rejected under 35 U.S.C. 103(a) as being unpatentable over *Saia et al.* are requested in accordance with the following remarks.

Applicants respectfully assert that the circuit component claimed in claim 231

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patentably distinguishes over the citations by Saia et al (US 5,874,770).

Saia et al. teach a circuit component comprising a first die 44 having a top surface at a horizontal level; a patterned wiring layer 47, 48 and 52 over said horizontal level,
5 wherein said patterned wiring layer 47, 48 and 52 comprises a portion across a side of said die; a passive device 28, 33 or 37 over said horizontal level; and a polymer layer 54 over said passive device 28, 33 or 37. ~ See Figs. 7-12; col. 6, lines 47-49; col. 7, line 66 through col. 8, line 8 ~

10 Saia et al. teach there are multiple polymer layers 42, 10 and 40 between said patterned wiring layer 47, 48 and 52 and said first die 44, said patterned wiring layer 47, 48 and 52 being connected to said first die 44 through an opening in said multiple polymer layers 42, 10 and 40. ~ See Fig. 12; col. 3, lines 62-65; col. 7, lines 1-8 and 13-16 ~ However, Saia et al. fail to teach hint or suggest there may be only one polymer
15 layer between said patterned wiring layer 47, 48 and 52 and said first die 44, as claimed in Claim 231. Withdrawal of rejection under 35 U.S.C.102(b) to Claim 231 is respectfully requested.

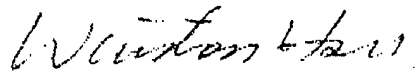
For at least the foregoing reasons, applicants respectfully submit independent
20 Claim 231 patently distinguishes over the prior art references, and should be allowed. For at least the same reasons, dependent Claims 232-237, 244-246, 256-277, 279 and 320 patently define over the prior art as well.

CONCLUSION

25 Some or all of the pending claims are believed to be in condition for allowance, and that is so requested.

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Sincerely yours,



Date: 03.12.2007

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- 10 Note: Please leave a message in my voice mail if you need to talk to me. (The time in D.C. is 12 hours behind the Taiwan time, i.e. 9 AM in D.C. = 9 PM in Taiwan.)

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